

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WENBIN LU	01/30/2018
LEE LI NI	01/31/2018
WILL YOUWEI SUN	01/31/2018
LEO LEI WANG	05/18/2018
RECEIVING PARTY DATA	
Name:	EMC IP HOLDING COMPANY LLC
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15884748
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	paula.hardilek@chamberlainlaw.com
Correspondent Name:	PAULA HARDILEK
Address Line 1:	1200 SMITH ST., 14TH FLOOR
Address Line 4:	HOUSTON, TEXAS 77002
ATTORNEY DOCKET NUMBER:	170360-019100US
NAME OF SUBMITTER:	ALY Z. DOSSA
SIGNATURE:	/Aly Z. Dossa/
DATE SIGNED:	05/23/2018
Total Attachments: 8	
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ASSIGNMENT

WHEREAS, we, Wenbin Lu, Timothy Bruce, Leo Lei Wang, Lee Li Ni and Will Youwei Sun, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled METHOD AND SYSTEM FOR EFFICIENT DATA REPLICATION IN BIG DATA ENVIRONMENT, the specification of which:

- is being executed on even date herewith and is about to be filed in the United States Patent Office;
- was filed on January 31, 2018 as U.S. Application No. 15/884,748;
- was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the Commonwealth of Massachusetts and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2018-Jan-30

Lu Wenbin
Inventor's Signature

Print full name of first inventor: Wenbin LU
Residence: Shanghai, China
Citizenship: China
Mailing Address: c/o EMC IP Holding Company LLC
176 South Street
Hopkinton, MA 01748

I, Piero Yao (name) whose residential address is
Yang Pu District Song Hu Road # 252 Building # 2 2nd floor
was personally present and did see Wenbin Lu (name of person signing
the assignment) who is personally known to me, execute the above assignment.

Piero Yao (signature of first witness)

Signed at Poll EMC China CoB (location of witness signature)

on this day 30 of 2018 (date of signature)

I, Hove Xu (name) whose residential address is
Yang Pu District Song Hu Road # 252 Building # 2 2nd floor
was personally present and did see Wenbin Lu (name of person signing
the assignment) who is personally known to me, execute the above assignment.

Hove Xu (signature of second witness)

Signed at Poll EMC China CoB (location of witness signature)

on this day 30 of 2018 (date of signature)

Date: 2018.1.31

Lee Li Ni
Inventor's Signature

Print full name of third inventor

Lee LINI

Residence:

Shanghai, China

Citizenship:

China

Mailing Address:

c/o EMC IP Holding Company LLC
176 South Street
Hopkinton, MA 01748

I XI B NIU (name) whose residential address is

Shanghai Pu Shan District

was personally present and did see Li Ni (name of person signing

the assignment) who is personally known to me, execute the above assignment.

XI B NIU (signature of first witness)

Signed at Shanghai Central Plaza (location of witness signature)

on this day JAN 31 of 2018. (date of signature)

I Yu Wen hao (name) whose residential address is

Shanghai Minhang district

was personally present and did see Li Ni (name of person signing
the assignment) who is personally known to me, execute the above assignment.

Yu Wen hao (signature of second witness)

Signed at Shanghai Central Plaza (location of witness signature)

on this day JAN 31 of 2018. (date of signature)

Date: 1/31/2018

孙有伟
Inventor's Signature

Print full name of third inventor:

Will Youwei Sun

Residence:

Shanghai, China

Citizenship:

China

Mailing Address:

c/o EMC IP Holding Company LLC
176 South Street
Hopkinton, MA 01748

I 戴俊 (name) whose residential address is
1701-6658 Dow Ave, Burnaby, BC, Canada
was personally present and did see Youwei Sun (name of person signing
the assignment) who is personally known to me, execute the above assignment.

戴俊 (signature of first witness)

Signed at Telus Garden (location of witness signature)

on this day Jan 31 of 2018. (date of signature)

I 周慧玲 (name) whose residential address is

2705-1068 Hornby street, Vancouver, BC, Canada

was personally present and did see Youwei Sun (name of person signing
the assignment) who is personally known to me, execute the above assignment.

周慧玲 (signature of second witness)

Signed at Telus Garden (location of witness signature)

on this day Jan 31 of 2018. (date of signature)

ASSIGNMENT

WHEREAS, we, Wenbin Lu, Timothy Bruce, Leo Lei Wang, Lee Li Ni and Will Youwei Sun, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled METHOD AND SYSTEM FOR EFFICIENT DATA REPLICATION IN BIG DATA ENVIRONMENT, the specification of which:

- is being executed on even date herewith and is about to be filed in the United States Patent Office;
- was filed on January 31, 2018 as U.S. Application No. 15/884,748;
- was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the Commonwealth of Massachusetts and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: May 18, 2018

Leo Lei WANG
Inventor's Signature

Print full name of third inventor:

Leo Lei WANG

Residence:

Shanghai, China

Citizenship:

China

Mailing Address:

c/o EMC IP Holding Company LLC
176 South Street
Hopkinton, MA 01748

I Yuan Luo (name) whose residential address is
Room 1201, Xin Cun Lane 1388, Putuo District, Shanghai
was personally present and did see Leo Lei WANG (name of person signing
the assignment) who is personally known to me, execute the above assignment.

Yuan Luo (signature of first witness)

Signed at Songhu Rd. 252, KIC1, 3F, Shanghai (location of witness signature)

on this day May 18 of 20 18. (date of signature)

I Dustin Mao (name) whose residential address is

Room 701, Unit 6, Lane 400 Miao Pu Road

was personally present and did see Leo Lei WANG (name of person signing
the assignment) who is personally known to me, execute the above assignment.

Dustin Mao (signature of second witness)

Signed at 752 Songhu Road, KIC1-3F, Shanghai (location of witness signature)

on this day May 18 of 20 18. (date of signature)